Contact Name Title - Contact Product-Env-Stewards Product-Enviro Compliance NA Product-Env-Stewards	ASSOCIATION CONNECTINIE ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name*  Company name*  Company unique ID  Unique ID Authority  Response Date*  2023-06-08  Contact Name  Title - Contact*  Phone - Contact*  Product-Env-Stewards  Produc	752-21.1											als and Mfg	Informati	on	
Semilar   Semi	upplier Inform	ation				·									
Title - Contact Name Product Envis Compliance NA Nanifacturing Site Nanifac	Company name*				Company unique ID			Unique ID Authority				Response Date*			
Product-Env-Stewards	nsemi											2023-06-08			
Authorized Representative*  Product-Env-Stewards  Product Enviro Compliance  Requester Item Number  Mfr Item Number  Mfr Item Number  Mfr Item Name  Effective Date  Version  Manufacturing Site  Weight*  UOM  Unit  One Substitute of Reflow Cycles  Manufacturing Proccess Information  Terminal Plating / Grid Array Material  Terminal Base Alloy  Matte Tin (Sn) - annealed  CU Alloy  Title - Representative  Phone - Representative*  NA  Product-Env-Stewards@onsemi.com  Manufacturing Site  Weight*  UOM  Unit  One Substitute of Reflow Cycles  Phone - Representative*  Product-Env-Stewards@onsemi.com  Manufacturing Site  Weight*  UOM  Unit  One Substitute of Reflow Cycles  Authorized Representative*  Product-Env-Stewards@onsemi.com  Manufacturing Site  Weight*  UoM  Unit  One Substitute of Reflow Cycles  One Substitute of Re	ontact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Stewards  Requester Item Number  Mfr Item Number  Mfr Item Number  Mfr Item Name  Effective Date  Version  Manufacturing Site  Weight*  UOM  Unit  2023-06-08  PH1  70.33  mg  Each  Manufacturing Process Information  Terminal Plating / Grid Array Material  Terminal Base Alloy  Terminal Base Alloy  Terminal Plating / Grid Array Material  Terminal Base Alloy  Terminal Base Alloy  Terminal Plating / Grid Array Material  Terminal Base Alloy  Terminal Base Allo	Product-Env-Stewa	rds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	uthorized Represe	ntative*	Title - Representative			I	Phone - Representative*			Email - Representative*					
SMDA05CDR2G 4 CHAN BIDIRECTIONAL TVS 2023-06-08 PH1 70.33 mg Each    Terminal Plating / Grid Array Material   Terminal Base Alloy   J-STD-020 MSL Rating   Peak Process Body Temperature   Max Time at Peak Temperature   Number of Reflow Cycles	Product-Env-Stewa	rds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles  Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requeste	Requester Item Number Mfr		r Item Number Mfr Item Name				Effective Date	Version	Version Manufacturing Site		W	eight*	UOM	Unit Type
Terminal Plating / Grid Array Material  Terminal Base Alloy  J-STD-020 MSL Rating  Peak Process Body Temperature  Max Time at Peak Temperature  Number of Reflow Cycles  260  C 30  Seconds  3  Somments			SMDA05	CDR2G	4 CHAN BIDIREC	CTIONAL TVS	s	2023-06-08		F	PH1	70	.33	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 comments				arminal Resa	Alloy	STD 020 MSI	Pating	Dank Den	cass Rody 7	Camparatur	May Time at Pools	Tamparatur	a Numb	ar of Patlow Cya	lac
omments	2 ,			· ·		L Kaung						er or Kerlow Cyc	ies		
	•	i (Sii) - aimealeu	C	U Alloy	1			400		IC	30	seconds	3		
ver 1 - maximum ume at peak temperature during soldering is 10-30 seconds		ima at maak tammanatuna	duning sale	domina ia 10.2	20 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.91	mg	Supplier	Silicon (Si)	7440-21-3		1.91	mg
Die Attach	0.19	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.0608	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.1292	mg
Lead Frame	37.61		Supplier	Silver (Ag)	7440-22-4		0.7898	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0752	mg
			Supplier	Iron (Fe)	7439-89-6		0.9403	mg
			Supplier	Copper (Cu)	7440-50-8		35.8047	mg
Mold Compound-Black	28.58	mg		Epoxy resin	proprietary data		2.0006	mg
			Supplier	Phenolic Resin	Proprietary Data		2.0006	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		4.287	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1429	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		20.1489	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond - Au	0.15	mg	Supplier	Gold (Au)	7440-57-5		0.15	mg